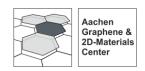




Agenda for the Workshop "Wafer-scale Integration of 2D materials" 12th to 13th November 2019, Forum M Aachen

	Tuesday 12 th November
12:00-13:00	Welcome Reception (Lunch)
	Session Chair – Satender Kataria (RWTH)
13:00-13:10	Welcome and opening Daniel Neumaier
13:10-13:40	Electronic devices using TMDC's Maximilian Prechtl, Universität der Bundeswehr, München
13:40-14:10	First steps of 2D material integration in 300mm silicon production line Cedric Huyghebaert, IMEC, Belgium
14:10-14:40	MOVPE of TMDC and 2D-2D Heterostructures Holger Kalisch, RWTH Aachen University
14:40-15:00	Front-End-of-Line integration of Graphene oxide and Biosensors Vivek Pachauri, RWTH Aachen University
15:00-16:00	Coffee Break + Poster Session
	Session Chair – Zhenxing Wang (AMO)
16:00-16:30	On the stacking and flipping of high-quality graphene-based heterostructures Christoph Stampfer, RWTH Aachen University
16:30-17:00	Process engineering for wafer-level integration of graphene into industrial applications Sebastian Wittmann, Infineon Technologies, Regensburg
17:00-17:20	Progress in large-scale transfer of graphene and 2D materials Abhay Shivayogimath, DTU, Denmark
17:20-17:50	Large-Area Integration of Two-Dimensional Materials and Their Heterostructures by Wafer Bonding Arne Quellmalz, KTH Royal Institute of Technology, Sweden
19:30-22:00	Dinner – Place to be announced (walking distance from the venue)













	Wednesday 13 th November
	Session Chair – Daniel Neumaier (AMO)
9:00-9:25	Graphene biosensors with CMOS readout Sanna Arpiainen, VTT Technical Research Centre of Finland
9:25-9:50	200 mm graphene growth and transfer for integration in microelectronics Rasuole Lukose, IHP, Frankfurt (Oder)
9:50-10:15	Wafer scale graphene processing – Progress at AMO Zhenxing Wang, AMO GmbH, Aachen
10:15-10:40	Graphene Integration Challenges Amaia Zurutuza, Graphenea, Spain
10:40-11:10	Coffee Break + Poster Session
	Session Chair - Max Lemme (AMO/RWTH)
11:10-11:30	Graphene back-end-of-line integration requirements for image sensors Stijn Goosens, ICFO, Spain
11:30-12:00	GIMMIK: Graphene Technology on 200 mm Wafer for Microelectronic Applications Michael Heuken, AIXTRON, Aachen
12:00-12:30	CaF2 Insulators for Ultrascaled 2D Field Effect Transistors Tibor Grasser, Tu Wien, Austria
12:30-13:00	Monitoring of Graphene key control characteristics by THz wafer scanning systems Michael Nagel, Protemics, Aachen
13:00-14:00	Lunch
14:00-16:30	Tour at AIXTRON: Bus transfer from the venue is organized. If you want to join the tour, please send an e-mail until Oct 31 to: amjadi@amo.de

ACKNOWLEDGEMENTS

The workshop is financially supported by the European Commission under the projects G-Imager, ORIGENAL, QUEFORMAL and ULISSES, and by the German Federal Ministry of Education and Research (BMBF) within the projects GIMMIK and NobleNEMS.



